

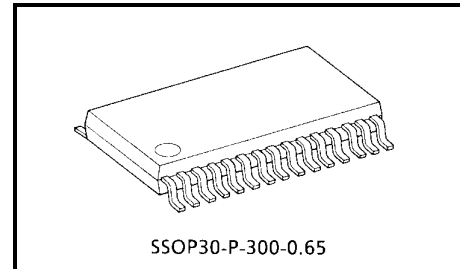
TA2160FNG

Low Consumption Current Stereo Headphone Amplifier (1.5/3 V use)

The TA2160FNG is low consumption current stereo headphone amplifier IC for headphone stereo. It is suitable for 1.5 V or 3 V headphone stereo.

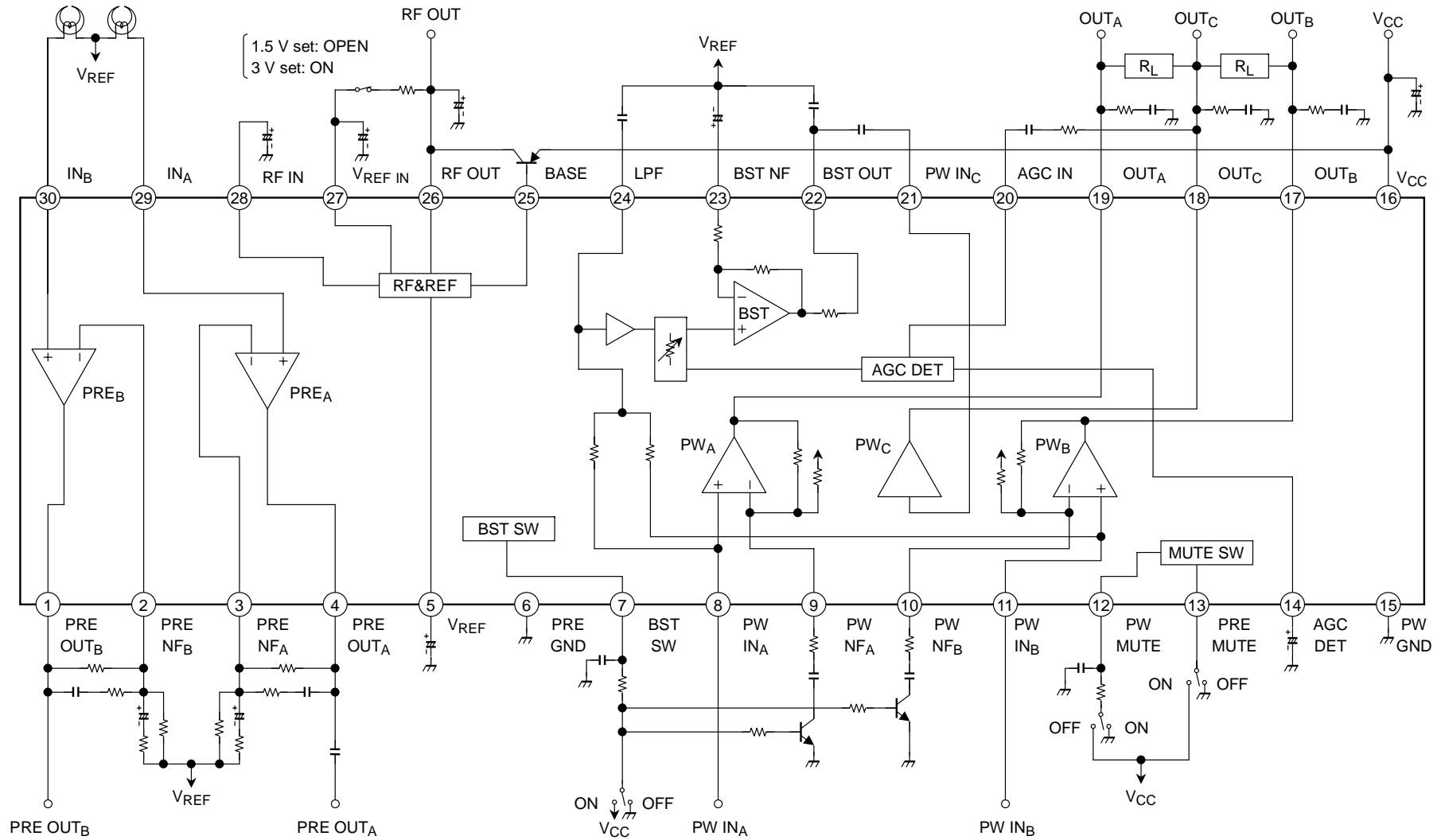
Features

- Low consumption current
Current value ($f = 1 \text{ kHz}$, $R_L = 32 \Omega$, $T_a = 25^\circ\text{C}$, typ.)
 - $V_{CC} = 1.3 \text{ V}$
 $ICCQ = 1.6 \text{ mA}$ (No signal)
 $ICC = 4.6 \text{ mA}$ ($0.1 \text{ mW} \times 2 \text{ ch}$)
 $ICC = 8.6 \text{ mA}$ ($0.5 \text{ mW} \times 2 \text{ ch}$)
 - $V_{CC} = 3 \text{ V}$
 $ICCQ = 3.0 \text{ mA}$ (No signal)
 $ICC = 4.8 \text{ mA}$ ($0.1 \text{ mW} \times 2 \text{ ch}$)
 $ICC = 8.8 \text{ mA}$ ($0.5 \text{ mW} \times 2 \text{ ch}$)
- Built-in ripple filter
- Pre-amplifier stage
 - Built-in input capacitor for reducing buzz noise
 - Input coupling condenser-less
 - Built-in pre-amplifier mute
- Power amplifier stage
 - Built-in bass boost function with AGC
 - Built-in treble boost function
 - Built-in input capacitor for reducing buzz noise
 - $GV = 25\text{dB}$ (typ.)
 - Built-in power amplifier mute
- Operating supply voltage range ($T_a = 25^\circ\text{C}$)
 $V_{CC(\text{opr})} = 0.95 \text{ to } 4.5 \text{ V}$

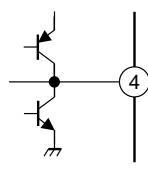
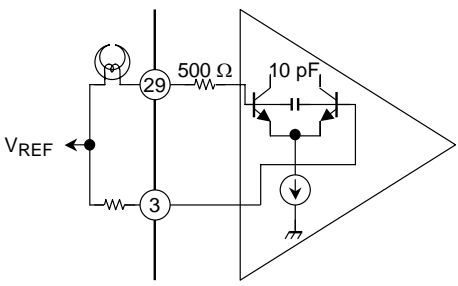
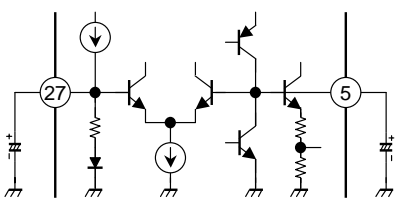
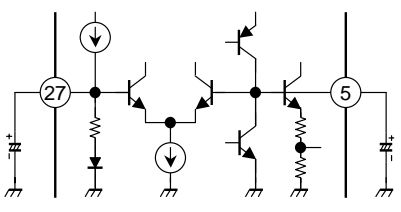
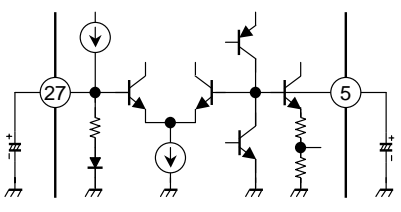
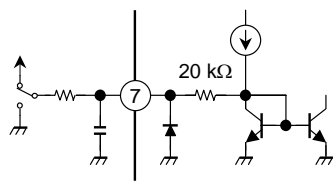


Weight: 0.17 g (typ.)

Block Diagram



Terminal Explanation (terminal voltage: typical terminal voltage at no signal with test circuit, $V_{CC} = 1.3\text{ V}$, $T_a = 25^\circ\text{C}$)

Terminal		Function	Internal Circuit	Terminal Voltage (V)
No.	Name			
1	PRE OUT _B	Input of preamplifier		0.44
4	PRE OUT _A			0.56
17	OUT _B	Output of power amplifier		0.7
18	OUT _C			0.73
19	OUT _A			0.73
2	PRE NF _B	NF of preamplifier		0.73
3	PRE NF _A			0.73
29	IN _A	Input of preamplifier		0.73
30	IN _B			0.73
5	V _{REF}	Reference circuit		0.73
27	V _{REF IN}	Input of reference circuit		0.73
6	PRE GND	—	—	0
7	BST SW	Boost on/off switch (BST on: H level or open BST off: L level) Refer to application note 3 (2) This switch is the control terminal of the bass boost function. When it is synchronized with treble boost function, the external connection with the PW NF terminal is required. Refer to application circuit.		—
12	PW MUTE	Muting switch of power amplifier (PW MUTE OFF: H level or open PW MUTE ON: L level) Refer to application note 3 (2)	—	—

Terminal		Function	Internal Circuit	Terminal Voltage (V)
No.	Name			
8	PW IN _A	Input of power amplifier (This terminal also has function of ADD amplifier input.)		0.73
11	PW IN _B			0.72
9	PW NF _A	NF of power amplifier		—
10	PW NF _B			—
13	PRE MUTE	Muting switch of preamplifier PRE MUTE ON: H level PRE MUTE OFF: L level Refer to application note 3 (2)		—
14	AGC DET	Smoothing terminal of boost AGC circuit		—
15	PW GND	Power GND for power drive stage	—	0
16	V _{CC}	—		1.3
25	BASE	Base biasing terminal of transistor for ripple filter		0.6
26	RF OUT	Output of ripple filter Ripple filter circuit supplies internal circuit except power drive stage with power source		1.24
28	RF IN	Ripple filter terminal		1.24

Terminal		Function	Internal Circuit	Terminal Voltage (V)
No.	Name			
20	AGC IN	Input of boost AGC circuit The input level to the boost amplifier is controlled by the input level of this terminal. Input impedance: 22 kΩ (typ.)		—
21	PW INC	Input of center amplifier		0.73
22	BST OUT	Output of boost amplifier		0.73
23	BST NF	NF of boost amplifier		0.73
24	LPF	Low pass filter terminal of bass boost		0.73

Application Note

1. Preamplifier Stage

Output DC voltage of preamplifier

Output DC voltage of preamplifier is determined by external resistors R1 and R2 as shown in Figure 1.

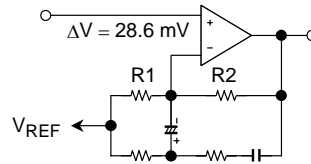


Figure 1 Output DC Voltage of Preamplifier

$$V_O (PRE) = V_{REF} - \Delta V \times (R2/R1 + 1)$$

- $V_{REF} = 0.73 \text{ V (typ.)}$
 V_{REF} is changed when resistance is connected between RF OUT terminal and V_{REF} IN terminal (Refer to application note 3 (1)).
- ΔV is an offset voltage which is designed to 28.6 mV.

It is as follows in case that the DC voltage is calculated by the constant of a test circuit.

$$\begin{aligned} V_O (PRE) &= 0.73 \text{ V} - 28.6 \text{ mV} (200 \text{ k}\Omega/22 \text{ k}\Omega + 1) \\ &= 0.44 \text{ V} \end{aligned}$$

Output DC voltage of preamplifier should be fixed about $V_{CC}/2$, because preamplifier get a enough dynamic range.

2. Power Amplifier Stage

(1) Input of power amplifier

Each input signal should be applied through a capacitor. In case that DC current or DC voltage is applied to each amplifier, the internal circuit has unbalance and the each amplifier doesn't operate normally.

It is advised that input signal refer to V_{REF} voltage, in order to reduce a pop noise or low frequency leak.

(2) Bass boost function

(a) System

This IC has the bass boost function in power amplifier stage. After this system adds the low frequency ingredient of side amplifier, it is applied into the center amplifier. And the bass boost level is controlled by the variable impedance circuit (Figure 2)

- Flow of the bass boost signal
 Variable impedance circuit → Boost amplifier → Center amplifier
- Flow of the bass boost level
 Output of center amplifier → AGC DET (level detection) → Variable impedance circuit operation

The system of treble boost function is realized by frequency characteristic adjustment of the side amplifier.

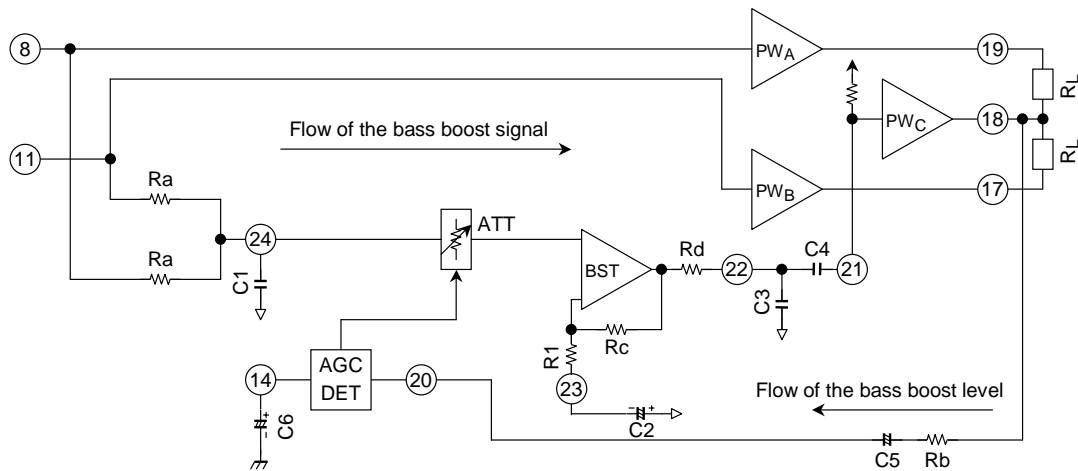


Figure 2 Bass Boost System

(b) AGC circuit

The AGC circuit of bass boost function is realized by the variable impedance circuit. The AGC DET circuit detects the low frequency level of center amplifier. When this level becomes high, the variable impedance circuit operates, and this circuit attenuates the input level of center amplifier.

The AGC DET circuit is the current input, so that the output voltage of ADD amplifier is changed into the current ingredient by resistor R_b and capacitor C_5 which are shown in Figure 2. And it is smoothed and detected by DET circuit (pin 14). And the direct current should not be applied to the AGC IN circuit, because, as for the circuit, the sensitivity setup is high.

Moreover, the AGC signal level is decreased in case that the resistor R_5 is connected with the capacitor C_5 in series. And the AGC point can be changed. But the center amplifier is clipped in the low frequency in case that the resistor R_5 is larger.

(c) Bass boost

The signal flow of bass boost function is as follows, refer to Figure 3.

LPF (internal resistors $2R_1$ and external capacitor C_1)

→ ATT (variable impedance circuit)

→ HPF (BST amplifier)

→ BPF (LPF: internal resistor R_4 and external capacitor C_3 , HPF: external capacitor C_4 and internal resistor R_5)

→ Center amplifier

The center amplifier signal becomes the reverse phase, because the phase of audio frequency range is reversed with two LPFs.

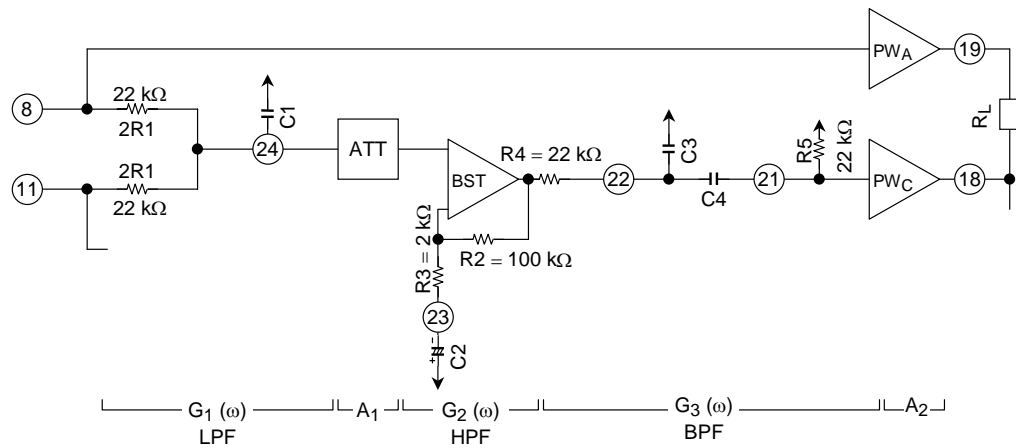


Figure 3 Block Diagram of Bass Boost

The transfer function of bass boost is as follows from Figure 3.

$$G(\omega) = G_1(\omega) \cdot A_1 \cdot G_2(\omega) \cdot G_3(\omega) \cdot A_2$$

The bass boost effect is changed by external resistor or external capacitor. The transfer function and cutoff frequency are as follows.

i Transfer function of LPF

$$G_1(\omega) = 1/(1 + j\omega C_1 \cdot R_1)$$

$$f_L = 1/2\pi C_1 \cdot R_1$$

ii Transfer function of BPF

$$G_3(\omega) = j\omega C_4 \cdot R_5 / [1 + j\omega (R_4 \cdot C_3 + R_5 \cdot C_3 + C_4 \cdot R_4) - \omega^2 R_4 \cdot C_3 \cdot R_5 \cdot C_4]$$

$$f_0 = 1/2\pi \sqrt{R_4 \cdot C_3 \cdot R_5 \cdot C_4}$$

iii HPF gain and ct of frequency

$$G_2(\omega) = 1 + R_2/(R_3 + 1/j\omega C_2)$$

$$f_{HC} = 1/(2\pi R_3 \cdot C_2)$$

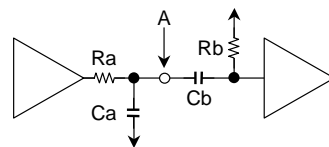
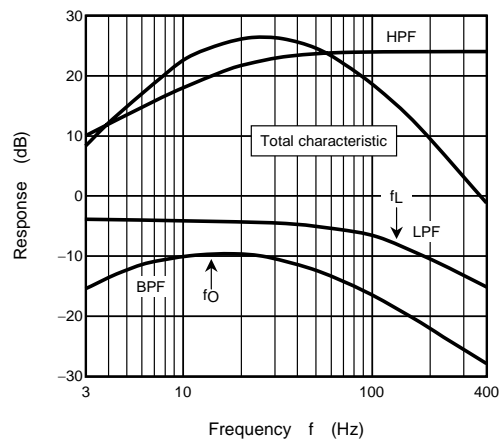


Figure 4 BPF



Graph 1 Characteristic of Bass Boost

- iv f_0 and f_L
 The f_L and f_0 should be set up out of the audio frequency range. In case that the f_0 and f_L is inside of audio frequency range and AGC circuit operates, the voltage gain decrease.
- v HPF
 The f_{HC} should be made 1/2 or less frequency as compared with the f_L and f_0 . The phase difference is large near the f_{HC} , so that the bass boost level runs short. And the HPF gain of middle or high frequency range should be set to 10dB or more.

- (3) Treble boost function
 This function is realized by using the PW NF terminal. For details, please refer to application note.

3. Total

- (1) Changeover of power amplifier output DC voltage at 3 V set.
 The output DC voltage of the power amplifier is raised by the resistance connected between the RF OUT terminal and the VREF IN terminal.
 In case of 3 V set, the dynamic range spreads.

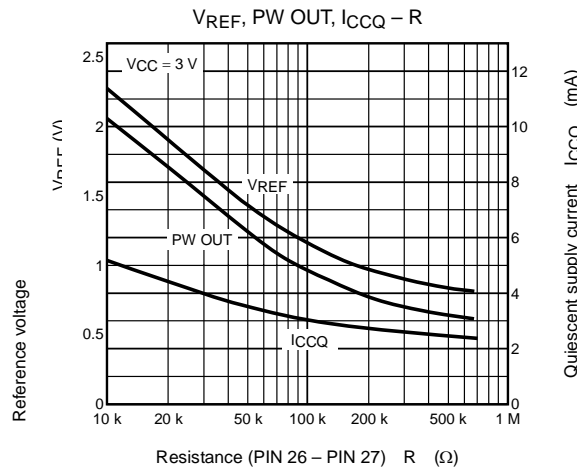


Figure 5 Adjutment of output DC voltage

- (2) Switch
 - (a) Switch terminal
 The current flows through each terminal, in case that these terminals are connected with H level independently, even though the IC off mode.
 It is necessary to connect an external pull-down resistor with each terminal in case that IC is turned on due to external noise etc. The sensitivity of each switch is set up highly.
 - (b) Pop noise
 It is advised to connect R and C with each switch, to reduce the pop noise in switchover (see Fig.1). It is better that the constants are $R = 100 \text{ k}\Omega$, $C = 1 \text{ }\mu\text{F}$. As for the constants, select the optimum one depending on each a set carefully.

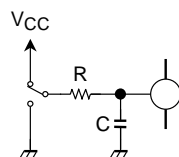
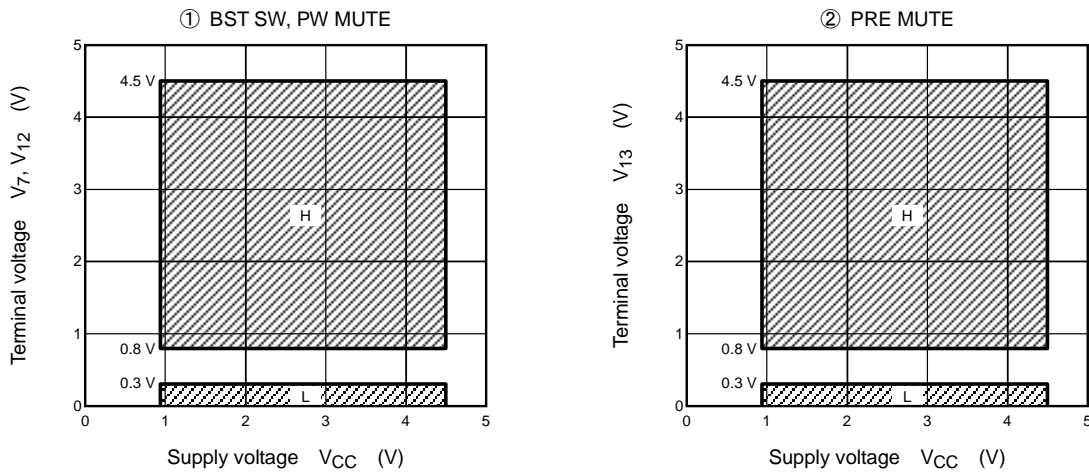


Figure 6 Pop noise

(c) Sensitivity voltage of each switch ($T_a = 25^\circ\text{C}$)



	BST SW (V_7)	PW MUTE (V_{12})
H level/open	BST ON	Power mute off
L level	BST OFF	Power mute on

	PRE MUTE (V_{13})
H level	Pre mute on
L level	Pre mute off

(3) Ripple filter

It is necessary to connect a low saturation transistor (2SA1362 etc.) for ripple filter, because this IC doesn't have transistor for ripple filter. Care should be taken to stabilize the ripple filter circuit, because the ripple filter circuit supplies internal circuit except power drive stage with power source.

(4) Capacitor

Small temperature coefficient and excellent frequency characteristic is needed by capacitor below.

- Oscillation preventing capacitors for power amplifier output
- Capacitor between V_{REF} and GND
- Capacitor between V_{CC} and GND
- Capacitor between RF OUT and GND

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	4.5	V
Output current	I_O (peak)	100	mA
Power dissipation	P_D (Note)	550	mW
Operating temperature	T_{opr}	-25~75	$^\circ\text{C}$
Storage temperature	T_{stg}	-55~150	$^\circ\text{C}$

Note: Derated above $T_a = 25^\circ\text{C}$ in proportion of 4.4 mW/ $^\circ\text{C}$.

Electrical Characteristics

(unless otherwise specified, $V_{CC} = 1.3 \text{ V}$, $T_a = 25^\circ\text{C}$, $f = 1 \text{ kHz}$, SW1: a, SW3: a, SW4: a, SW5: OPEN)

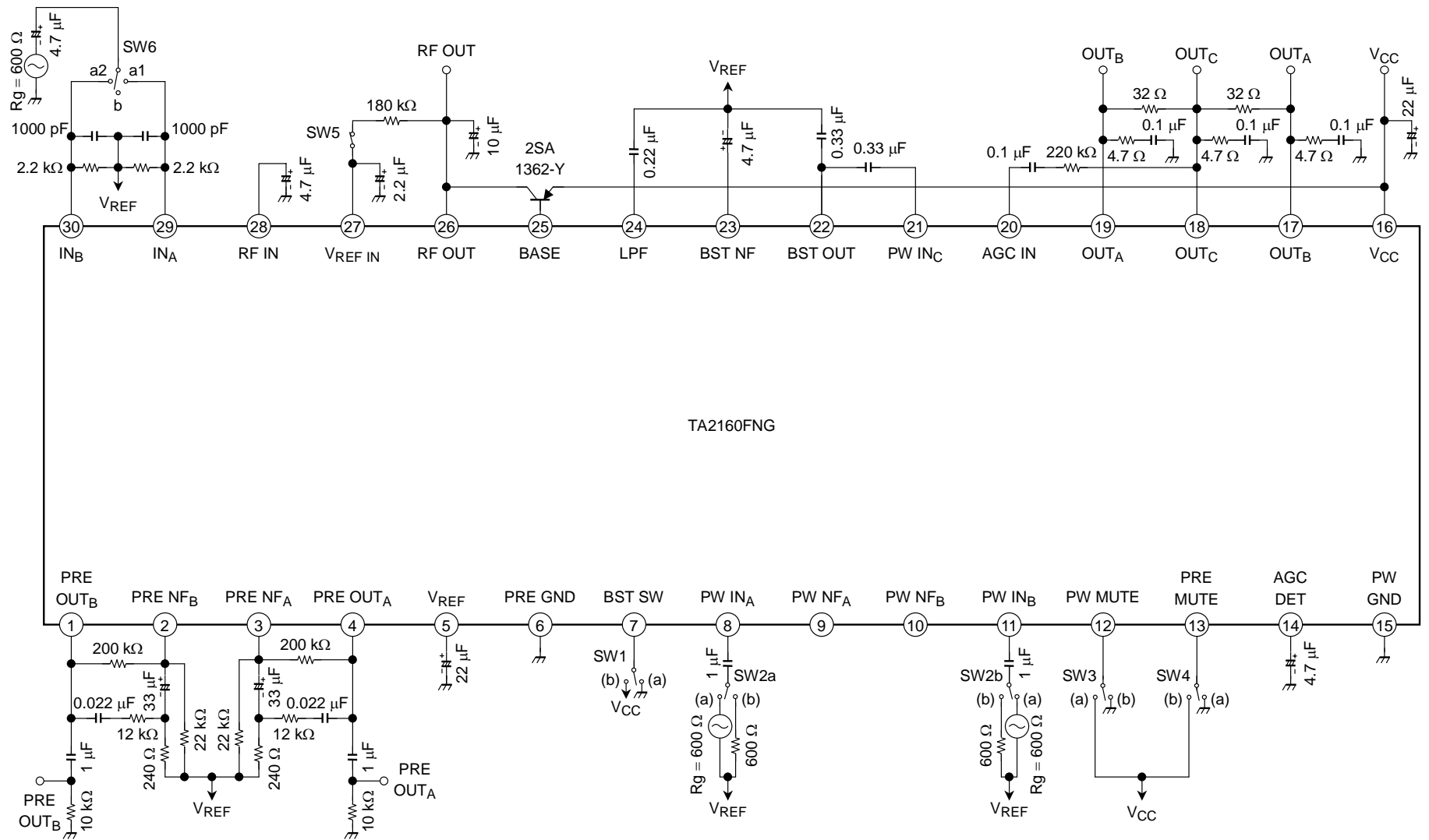
Preamplifier stage: $R_g = 2.2 \text{ k}\Omega$, $R_L = 10 \text{ k}\Omega$, SW6: a

Power amplifier stage: $R_g = 600 \Omega$, $R_L = 32 \Omega$, SW2: a)

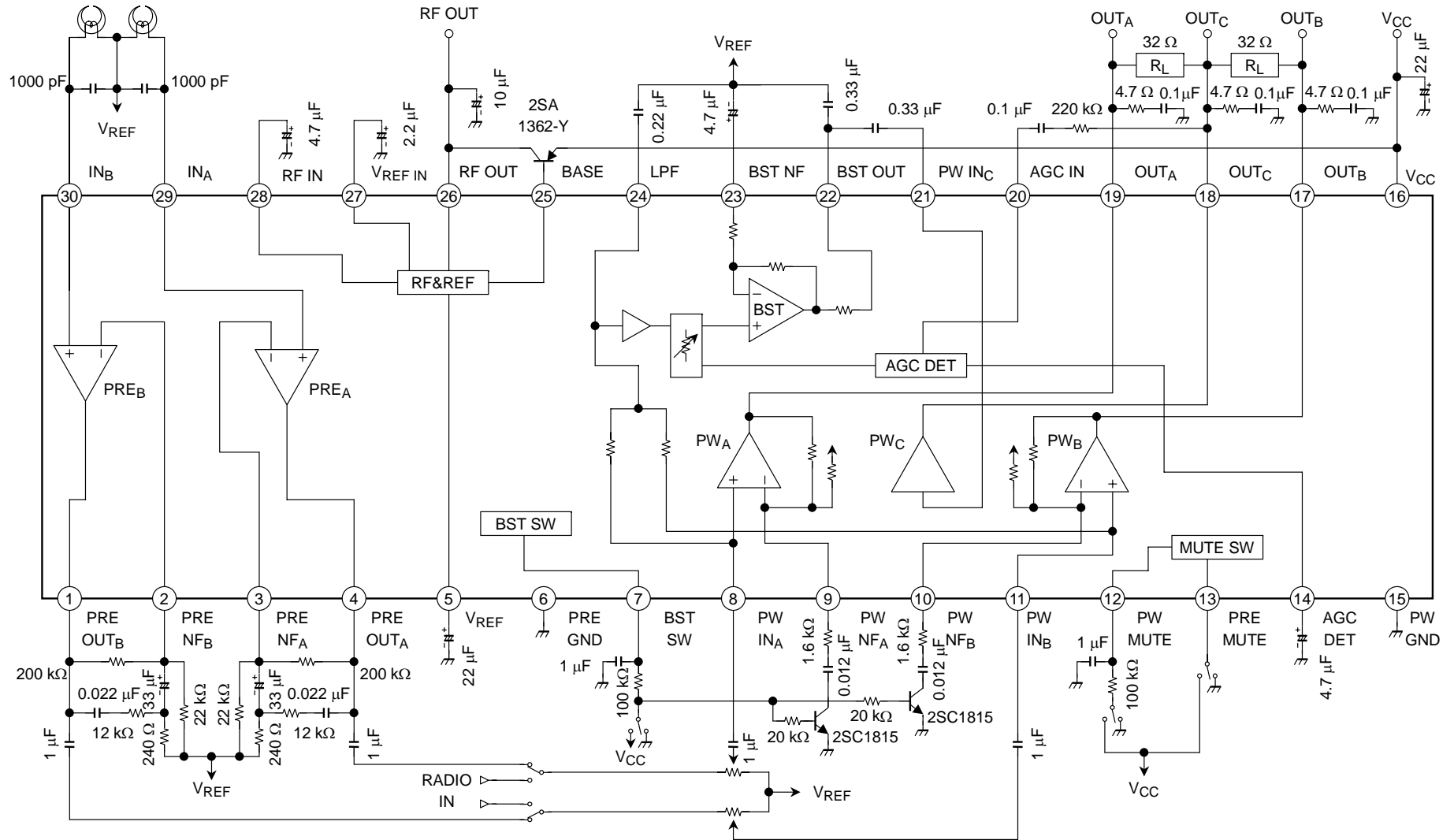
Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Quiescent supply current		I_{CCQ1}		PRE + PW	—	1.6	3.0	mA
		I_{CCQ2}		PRE: OFF, SW4: b	—	1.3	2.4	
		I_{CCQ3}		$V_{CC} = 3 \text{ V}$, PRE + PW, SW5: ON	—	3.0	5.5	
		I_{CCQ4}	—	$V_{CC} = 3 \text{ V}$, PRE: OFF, SW4: b, SW5: ON	—	2.7	5.0	
Power supply current during drive		I_{CC1}	—	PRE + PW, 0.1 mW/32 $\Omega \times 2$ ch	—	4.6	—	mA
		I_{CC2}	—	$V_{CC} = 3 \text{ V}$, PRE + PW, 0.1 mW/32 $\Omega \times 2$ ch, SW5: ON	—	4.8	—	
Preamp. stage	Open loop voltage gain	G_{VO}	—	$V_o = -22\text{dBV}$, NF resistor (240 Ω): short	65	80	—	dB
	Closed loop voltage gain	G_{VC}	—	$V_o = -22\text{dBV}$	—	35	—	dB
	Maximum output voltage	V_{om1}	—	THD = 1%	160	250	—	mVrms
	Total harmonic distortion	THD1	—	$V_{CC} = 1 \text{ V}$, $V_o = -22\text{dBV}$	—	0.1	0.3	%
	Equivalent input noise voltage	V_{ni}	—	$R_g = 2.2 \text{ k}\Omega$, DIN/AUDIO NAB ($G_V = 35 \text{ dB}$, $f = 1 \text{ kHz}$), SW6: b	—	1.5	2.7	μVrms
	Cross talk	CT1	—	$V_o = -22\text{dBV}$	—	60	—	dB
	Ripple Rejection ratio	RR1	—	$f_r = 100 \text{ Hz}$, $V_r = -32\text{dBV}$ BPF = 100 Hz	—	70	—	dB
	Preamp. muting attenuation	ATT1	—	$V_o = -22\text{dBV}$, SW4: a \rightarrow b	—	84	—	dB
Power amp. stage	Voltage gain	G_{V1}	—	$V_o = -22\text{dBV}$	23	25	27	dB
	Channel balance	CB	—	$V_o = -22\text{dBV}$	-1.5	0	+1.5	dB
	Output power	P_{o1}	—	$V_{CC} = 1.5 \text{ V}$, THD = 10%	3	6	—	mW
		P_{o2}	—	$V_{CC} = 3 \text{ V}$, THD = 10%, SW5: ON	8	12	—	
	Total harmonic distortion	THD2	—	$P_o = 1 \text{ mW}$	—	0.1	0.5	%
	Output noise voltage	V_{no}	—	$R_g = 600 \Omega$, DIN/AUDIO, SW2: b	—	30	60	μVrms
	Cross talk	CT2	—	$V_o = -22\text{dBV}$	34	43	—	dB
	Ripple rejection ratio	RR2	—	$V_{CC} = 1 \text{ V}$, $f_r = 100 \text{ Hz}$, $V_r = -32\text{dBV}$, BPF = 100 Hz	—	80	—	dB
Power amplifier muting attenuation	ATT2	—	$V_o = -22\text{dBV}$, SW3: a \rightarrow b	—	80	—	dB	
Boost stage	Voltage gain	G_{V2}	—	$f = 40 \text{ Hz}$, $V_{in} = -64\text{dBV}$, SW1: b, MONI: C-AMP - GND	45	48.5	52	dB
	Voltage gain	G_{V3}	—	$f = 40 \text{ Hz}$, $V_{in} = -47\text{dBV}$, SW1: b, MONI: C-AMP - GND	31	34.5	38	dB
	Maximum output voltage	V_{om2}	—	$f = 40 \text{ Hz}$, THD = 1%, SW1: b, MONI: C-AMP - GND	—	270	—	mVrms
	Muting attenuation	ATT3	—	$f = 40 \text{ Hz}$, $V_o = -32\text{dBV}$, SW1: b \rightarrow a	—	58	—	dB
Ripple filter output voltage	$V_{RF \text{ OUT}}$	—	$V_{CC} = 1 \text{ V}$, $I_{RF} = 20 \text{ mA}$	0.9	0.93	—	V	

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Ripple filter ripple rejection ration	RR3	—	$V_{CC} = 1\text{ V}$, $I_{RF} = 20\text{ mA}$ $f_r = 100\text{ Hz}$, $V_r = -32\text{ dBV}$ BPF = 100 Hz	35	42	—	dB
Preamplifier on voltage	V_{13}	—	$V_{CC} = 0.95\text{ V}$	0	—	0.3	V
Preamplifier off current	I_{13}	—		5	—	—	μA
Power amplifier on current	I_{12}	—		5	—	—	μA
Power amplifier off voltage	V_{12}	—		0	—	0.3	V
Boost switch on current	I_7	—		5	—	—	μA
Boost switch off voltage	V_7	—		0	—	0.3	V

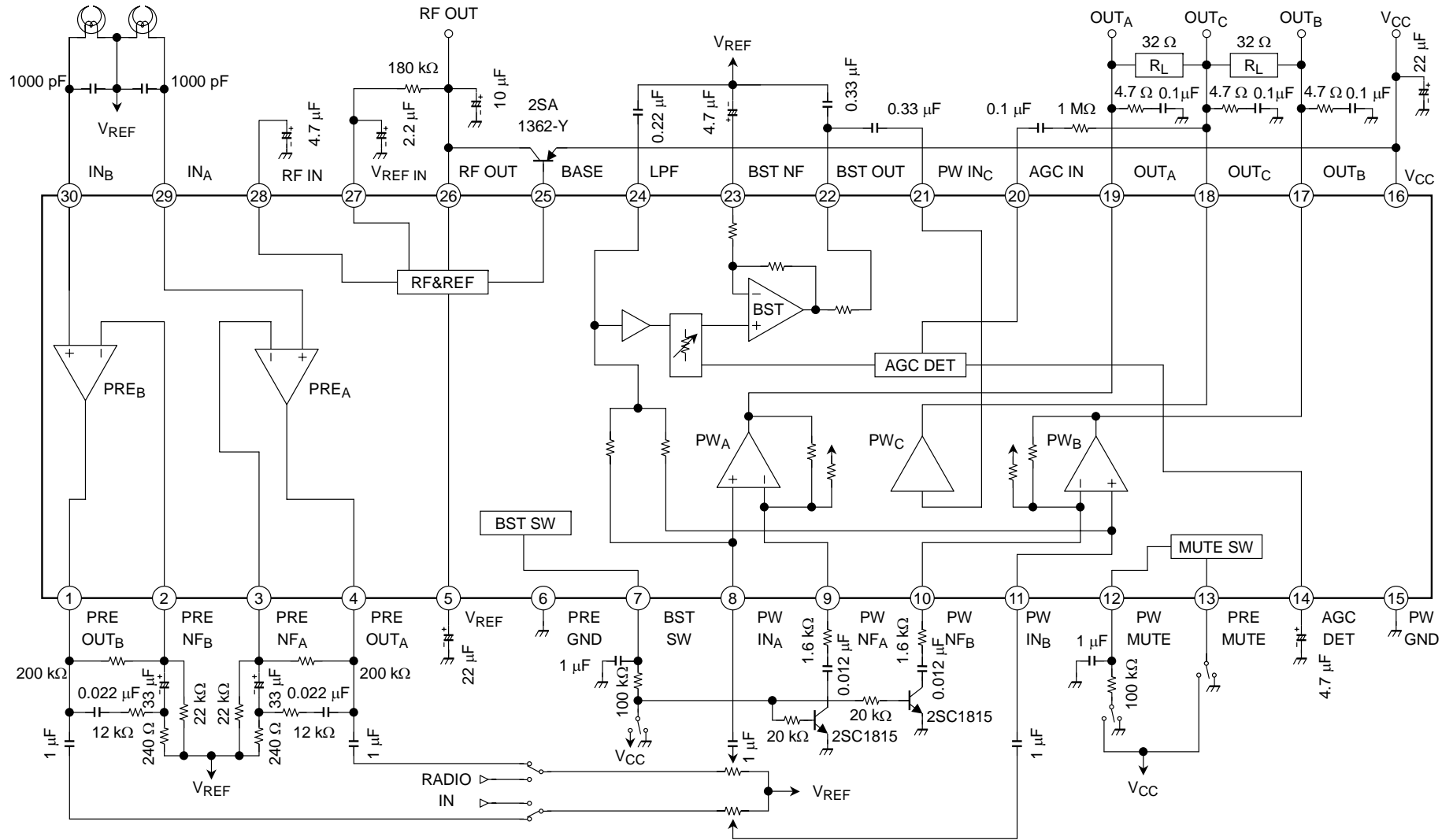
Test Circuit



Application Note 1 (1.5 V set)



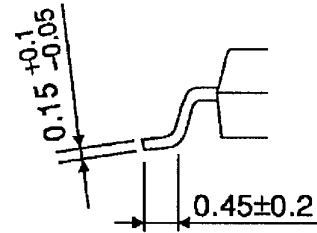
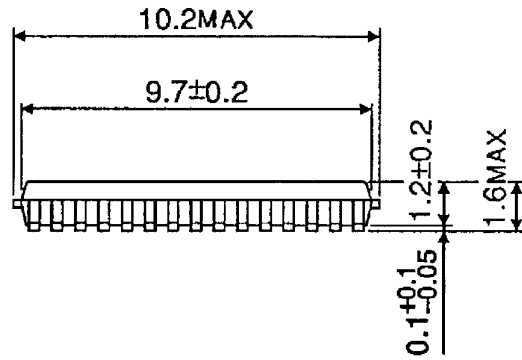
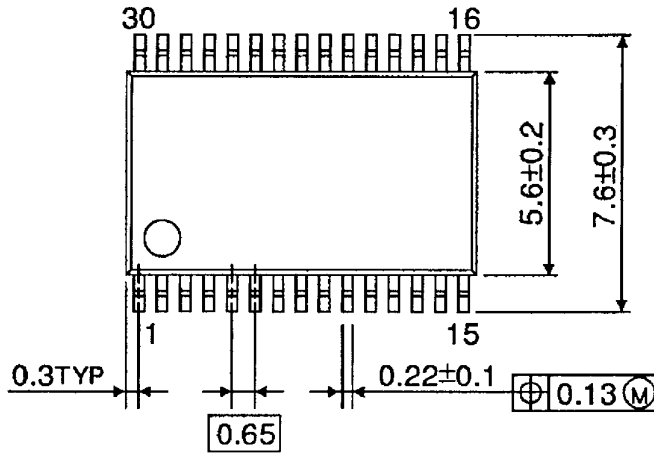
Application Note 2 (3 V Set)



Package Dimensions

SSOP30-P-300-0.65

Unit : mm



Weight: 0.17 g (typ.)

About solderability, following conditions were confirmed

- Solderability

- (1) Use of Sn-63Pb solder Bath

- solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux

- (2) Use of Sn-3.0Ag-0.5Cu solder Bath

- solder bath temperature = 245°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux

RESTRICTIONS ON PRODUCT USE

030619EBA

- The information contained herein is subject to change without notice.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- TOSHIBA products should not be embedded to the downstream products which are prohibited to be produced and sold, under any law and regulations.